## PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data		
1.1 Company	<b>577</b>	STMicroelectronics International N.V
1.2 PCI No.		AMS/20/12107
1.3 Title of PCI		Qualification of a new Matrix density lead frame and a new material set in ST Shenzhen for selected products assembled in DPAK package
1.4 Product Category		LDF33DT-TR
1.5 Issue date		2020-04-17

2. PCI Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Giuseppe LISI

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	(Not Defined)	ST Shenzhen

	4. Description of change	
	Old	New
4.1 Description	- Standard density lead-frame - Gold wire	- Matrix density lead-frame - Copper wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change	
5.1 Motivation	This PCI on DPAK product (LDF33DT-TR) follows the PCN 10764 that ST sent in March 2018 to announce the change of lead frame and wire material for PPAK packages. This change will allow us to increase efficiency and production capacity. Customers demand will be better supported.
5.2 Customer Benefit	SERVICE IMPROVEMENT

	6. Marking of parts / traceability of change
6.1 Description	New finished good codes

	7. Timing / schedule
7.1 Date of qualification results	2020-04-09
7.2 Intended start of delivery	2020-05-25
7.3 Qualification sample available?	Upon Request

	8. Qualification / Validation		
8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
12107 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LDF33DT-TR	



## **Public Products List**

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title: Qualification of a new Matrix density lead frame and a new material set in ST Shenzhen for selected products

assembled in DPAK package

PCI Reference: AMS/20/12107

Subject: Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

LDF33DT-TR
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